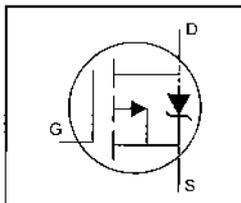


HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- Repetitive Avalanche Rated
- Surface Mount (IRFR9024)
- Straight Lead (IRFU9024)
- Available in Tape & Reel
- P-Channel
- Fast Switching



$$V_{DSS} = -60V$$

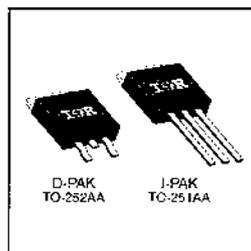
$$R_{DS(on)} = 0.28\Omega$$

$$I_D = -8.8A$$

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D-Pak is designed for surface mounting using vapor phase, infrared, or wave soldering techniques. The straight lead version (IRFU series) is for through-hole mounting applications. Power dissipation levels up to 1.5 watts are possible in typical surface mount applications.



DATA SHEETS

Absolute Maximum Ratings

Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$ Continuous Drain Current, $V_{GS} @ -10 V$	-8.8	A
$I_D @ T_C = 100^\circ C$ Continuous Drain Current, $V_{GS} @ -10 V$	-5.6	
I_{DM} Pulsed Drain Current ①	-35	
$P_D @ T_C = 25^\circ C$ Power Dissipation	42	W
$P_D @ T_A = 25^\circ C$ Power Dissipation (PCB Mount)**	2.5	
Linear Derating Factor	0.33	W/°C
Linear Derating Factor (PCB Mount)**	0.020	
V_{GS} Gate-to-Source Voltage	-20	V
E_{AS} Single Pulse Avalanche Energy ②	300	mJ
I_{AR} Avalanche Current ③	-8.8	A
E_{AR} Repetitive Avalanche Energy ④	5.0	mJ
dv/dt Peak Diode Recovery dv/dt ⑤	-4.5	V/ns
T_J, T_{STG} Junction and Storage Temperature Range	-55 to +150	°C
Soldering Temperature, for 10 seconds	260 (1.6mm from case)	

Thermal Resistance

Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$ Junction-to-Case	—	—	3.0	°C/W
$R_{\theta JA}$ Junction-to-Ambient (PCB mount)**	—	—	50	
$R_{\theta JA}$ Junction-to-Ambient	—	—	110	

** When mounted on 1" square PCB (FR-4 or G-10 Material).

For recommended footprint and soldering techniques refer to application note #AN-994.

IRFR9024, IRFU9024



Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
V _{DR(BSS)}	Drain-to-Source Breakdown Voltage	-60	—	—	V	V _{GS} =0V, I _D =-250μA
ΔV _{DR(BSS)/ΔT_J}	Breakdown Voltage Temp. Coefficient	—	-0.063	—	V/°C	Reference to 25°C, I _D =-1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance	—	—	0.28	Ω	V _{GS} =-10V, I _D =-5.3A ①
V _{GS(th)}	Gate Threshold Voltage	-2.0	—	-4.0	V	V _{DS} =V _{GS} , I _D =-250μA
g _{fs}	Forward Transconductance	2.9	—	—	S	V _{DS} =-25V, I _D =-5.3A ②
I _{DSS}	Drain-to-Source Leakage Current	—	—	-100	μA	V _{DS} =-60V, V _{GS} =0V
I _{SSS}	Gate-to-Source Forward Leakage	—	—	-500	μA	V _{GS} =-48V, V _{DS} =0V, T _J =125°C
I _{SSS}	Gate-to-Source Reverse Leakage	—	—	-100	nA	V _{GS} =-20V
Q _g	Total Gate Charge	—	—	19	nC	V _{DS} =-11A
Q _{gs}	Gate-to-Source Charge	—	—	5.4	nC	V _{DS} =-48V
Q _{gd}	Gate-to-Drain ("Miller") Charge	—	—	11	nC	V _{GS} =-10V ③
t _{don}	Turn-On Delay Time	—	13	—	ns	V _{DD} =-30V
t _r	Rise Time	—	68	—	ns	I _D =-11A
t _{d(off)}	Turn-Off Delay Time	—	15	—	ns	R _G =18Ω
t _f	Fall Time	—	29	—	ns	R _D =2.5Ω ④
L _D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact
L _S	Internal Source Inductance	—	7.5	—	nH	
C _{iss}	Input Capacitance	—	570	—	pF	V _{GS} =0V
C _{oss}	Output Capacitance	—	360	—	pF	V _{DS} =-25V
C _{rss}	Reverse Transfer Capacitance	—	65	—	pF	f=1.0MHz



Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	-8.8	A	MOSFET symbol showing the integral reverse p-n junction diode.
I _{SM}	Pulsed Source Current (Body Diode) ①	—	—	-35	A	
V _{SD}	Diode Forward Voltage	—	—	-6.3	V	T _J =25°C, I _S =-8.8A, V _{GS} =0V ②
t _{rr}	Reverse Recovery Time	—	100	200	ns	T _J =25°C, I _F =-11A
Q _{rr}	Reverse Recovery Charge	—	0.32	0.64	μC	di/dt=100A/μs ③
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L _S +L _D)				

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature
- ② V_{DD}=-25V, starting T_J=25°C, L=4.5mH, R_G=25Ω, I_{AS}=-8.8A
- ③ I_{SD}=-11A, di/dt≤140A/μs, V_{DD}<V_{DR(BSS)}, T_J≤150°C
- ④ Pulse width ≤ 300 μs, duty cycle ≤2%.

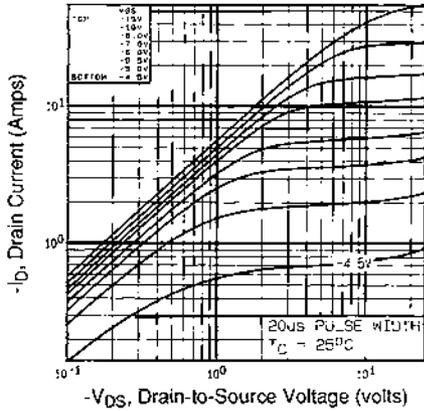


Fig 1. Typical Output Characteristics, $T_C=25^\circ\text{C}$

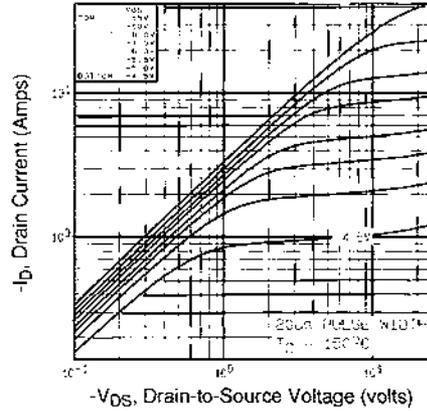


Fig 2. Typical Output Characteristics, $T_C=150^\circ\text{C}$

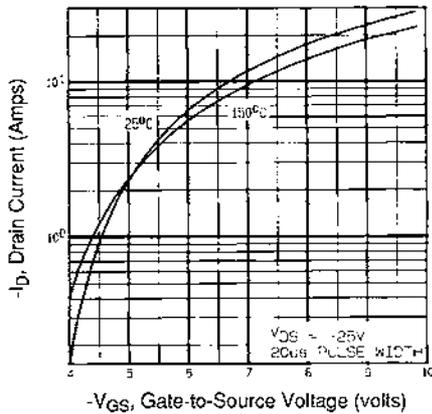


Fig 3. Typical Transfer Characteristics

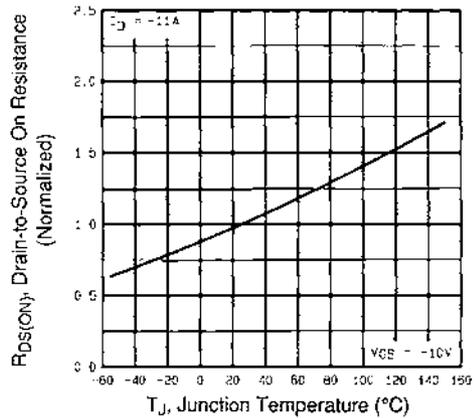


Fig 4. Normalized On-Resistance Vs. Temperature

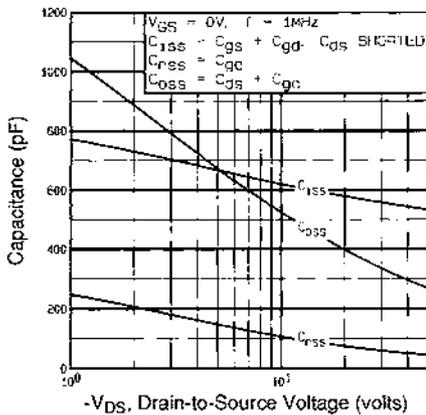


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

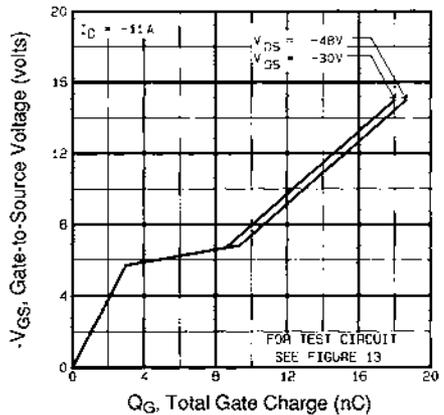


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

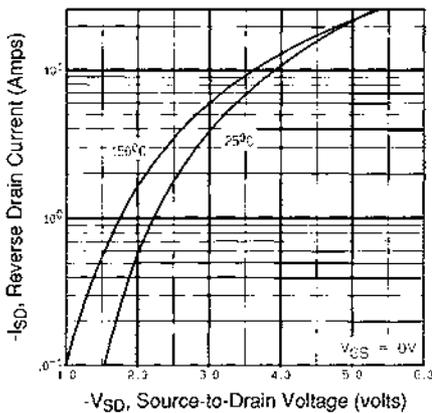


Fig 7. Typical Source-Drain Diode Forward Voltage

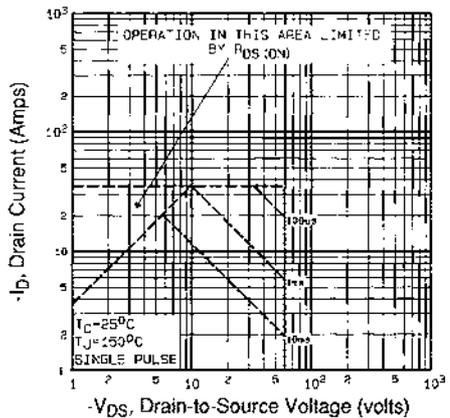


Fig 8. Maximum Safe Operating Area



IRFR9024, IRFU9024

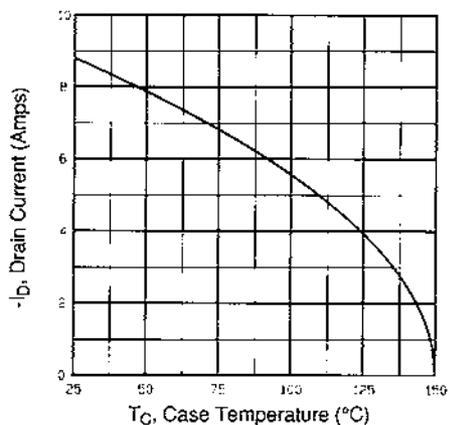


Fig 9. Maximum Drain Current Vs. Case Temperature

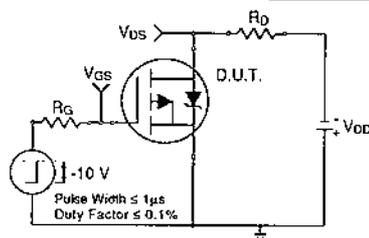


Fig 10a. Switching Time Test Circuit

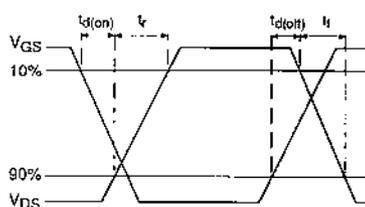


Fig 10b. Switching Time Waveforms

DATA SHEETS

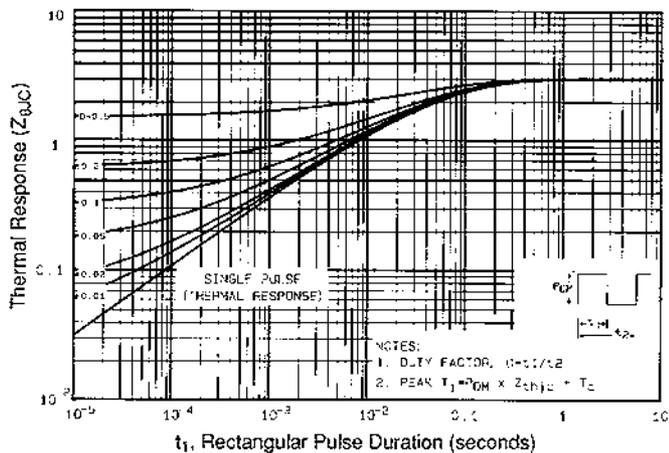


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

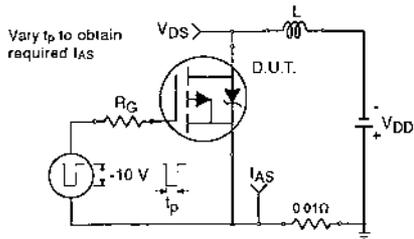


Fig 12a. Unclamped Inductive Test Circuit

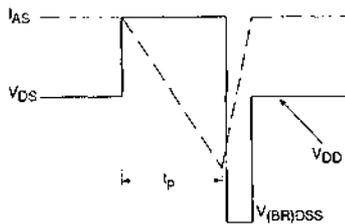


Fig 12b. Unclamped Inductive Waveforms

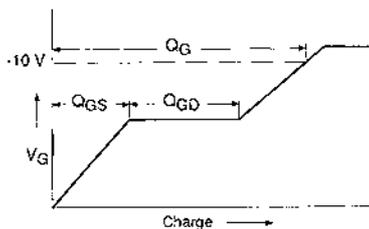


Fig 13a. Basic Gate Charge Waveform

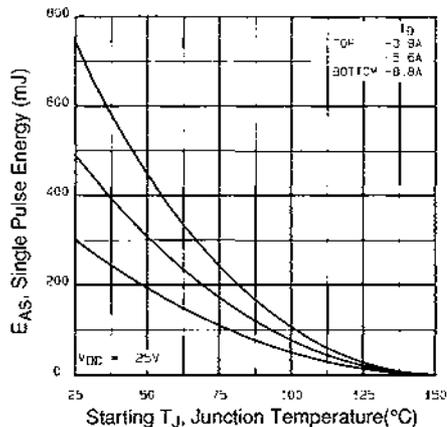


Fig 13c. Maximum Avalanche Energy Vs. Drain Current

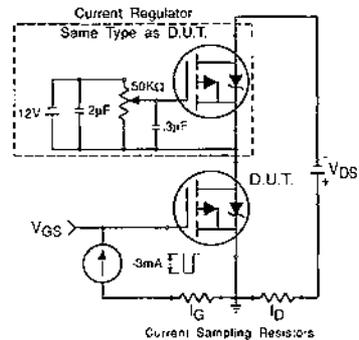


Fig 13b. Gate Charge Test Circuit

Appendix A: Figure 14, Peak Diode Recovery dv/dt Test Circuit – See page 1506

Appendix B: Package Outline Mechanical Drawing – See pages 1512, 1513

Appendix C: Part Marking Information – See page 1518

Appendix D: Tape & Reel Information – See page 1523